## **MOTOROLA** SEMICONDUCTOR TECHNICAL DATA



# **MRF237**

# The RF Line

#### NPN SILICON RF POWER TRANSISTOR

... designed for 12.5 Volt large-signal power amplifier applications in communication equipment operating to 225 MHz.

- Specified 12.5 Volt, 175 MHz Characteristics -Output Power = 4.0 Watts Minimum Gain = 12 dB Efficiency = 50%
- Characterized With Series Equivalent Large-Signal Impedance Parameters
- Grounded Emitter TO-39 Package for High Gain and Excellent Heat Dissipation
- Replaces Medium Power Stud Mount Devices

### MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Collector-Emitter Voltage	V <sub>CEO</sub>	18	Vdc
Collector-Base Voltage	V <sub>CBO</sub>	36	Vdc
Emitter-Base Voltage	VEBO	4.0	Vdc
Collector Current — Continuous	l <sub>C</sub>	1.0	Adc
Total Power Dissipation @ T <sub>C</sub> = 25 <sup>o</sup> C Derate above 25 <sup>o</sup> C	PD	8.0 45.7	Watts mW/ <sup>O</sup> C
Storage Temperature Range	T <sub>stg</sub>	-65 to +200	°C

## THERMAL CHARACTERISTICS

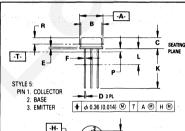
Characteristic	Symbol	Max	Unit
Thermal Resistance, Junction to Case	R <sub>θ</sub> JC	22	°C/W

## ELECTRICAL CHARACTERISTICS (T<sub>C</sub> = 25°C unless otherwise noted.)

Characteristic	Symbol	Min	Тур	Max	Unit
OFF CHARACTERISTICS					water the same
Collector-Emitter Breakdown Voltage (IC = 10 mAdc, IB = 0)	V(BR)CEO	18	-	-	Vdc
Collector-Emitter Breakdown Voltage (IC = 5.0 mAdc, VBE = 0)	V(BR)CES	36	-		Vdc
Emitter-Base Breakdown Voltage (I <sub>E</sub> = 1.0 mAdc, I <sub>C</sub> = 0)	V(BR)EBO	4.0	-	-,	Vdc
Collector Cutoff Current (V <sub>CB</sub> = 15 Vdc, I <sub>E</sub> = 0)	ІСВО		-	0.25	mAdc
ON CHARACTERISTICS					
DC Current Gain (I <sub>C</sub> = 250 mAdc, V <sub>CE</sub> = 5.0 Vdc)	pEE	5.0	-	-	. —
DYNAMIC CHARACTERISTICS					
Output Capacitance (V <sub>CB</sub> = 15 Vdc, I <sub>E</sub> = 0, f = 0.1 MHz)	Cob	-	15	20	pF
FUNCTIONAL TESTS				,	
Common-Emitter Amplifier Power Gain (P <sub>out</sub> = 4.0 W, V <sub>CC</sub> = 12.5 Vdc, f = 175 MHz)	GPE	12	14	_	dB
Collector Efficiency (P <sub>OUT</sub> = 4.0 W, V <sub>CC</sub> = 12.5 Vdc, f = 175 MHz)	η	50	62	-	%

4 W - 175 MHz RF POWER **TRANSISTOR** NPN SILICON





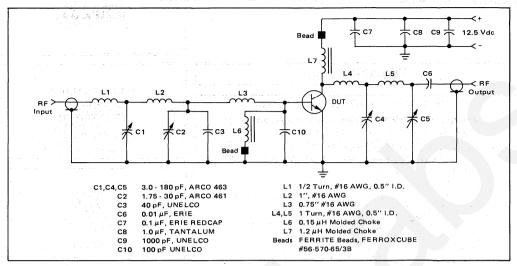


- 1. DIMENSIONING AND TOLERANCING PER ANSI
- CONTROLLING DIMENSION: INCH.
   DIMENSION J MEASURED FROM DIMENSION A
- 4. DIMENSION B SHALL NOT VARY MORE THAN 0.25 (0.010) IN ZONE R. THIS ZONE CONTROLLED FOR AUTOMATIC HANDLING.
- 5. DIMENSION F APPLIES BETWEEN DIMENSION P. AND L. DIMENSION D APPLIES BETWEEN DIMENSION L AND K MINIMUM. LEAD DIAMETER IS UNCONTROLLED IN DIMENSION P AND BEYOND DIMENSION K MINIMUM.

	MILLIN	IETERS	INCHES		
DIM	MIN	MAX	MIN	MAX	
Α	9.02	9.29	0.355	0.366	
В	8.01	8.50	0.315	0.335	
C	4.20	4.57	0.165	0.180	
D	0.44	0.53	0.017	0.021	
E	0.44	0.88	0.017	0.035	
F	0.41	0.48	0.016	0.019	
G	5.08 BSC		0.200 BSC		
Н	0.72	0.86	0.028	0.034	
J	0.74	1.01	0.029	0.040	
K	12.70	19.05	0.500	0.750	
L	6.35	-	0.250	_	
M	45° BSC		45° BSC		
P		1.27	_	0.050	
R	2.54	_	0.100		

**CASE 79-05** TO-206AF (TO-39)

#### FIGURE 1 - 175 MHz TEST CIRCUIT SCHEMATIC



#### FIGURE 2 - OUTPUT POWER versus INPUT POWER

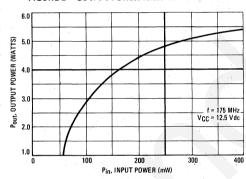


FIGURE 3 — OUTPUT POWER versus FREQUENCY

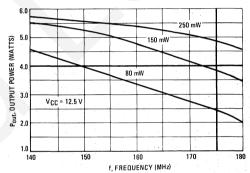


FIGURE 4 - OUTPUT POWER versus SUPPLY VOLTAGE

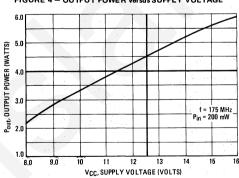
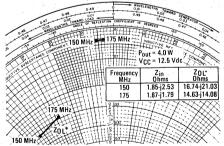


FIGURE 5 - SERIES EQUIVALENT IMPEDANCE



 $Z_{OL}^{\star}=C$ onjugate of the optimum load impedance into which the device output operates at a given output power, voltage and frequency.